Title: THERMAL PROTECTION FOR ELECTRONIC COMPONENTS DURING PROCESSING

Abstract: A method and device for cooling an electronic component (16) during its manufacture, repair, or rework. There is a cooling unit (10) in thermal communication with the electronic component (16) which extracts heat therefrom.
INTERNATIONAL SEARCH REPORT

A. CLASSIFICATION OF SUBJECT MATTER

IPC(7) : G01R 31/02
US CL : 324/760; 438/122

According to International Patent Classification (IPC) or to both national classification and IPC.

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
U.S. : 324/760; 438/122

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

C. DOCUMENTS CONSIDERED TO BE RELEVANT

<table>
<thead>
<tr>
<th>Category</th>
<th>Citation of document, with indication, where appropriate, of the relevant passages</th>
<th>Relevant to claim No.</th>
</tr>
</thead>
<tbody>
<tr>
<td>X</td>
<td>US 6,432,497 (BUNYAN) 13 August 2002 (13.08.2002), column 9, line 3 to column 13, line 51.</td>
<td>1-51</td>
</tr>
</tbody>
</table>

Further documents are listed in the continuation of Box C. See patent family annex.

Date of the actual completion of the international search: 09 January 2006 (09.01.2006)

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